WMED 2006 Announces Tutorials and an Extended March 17th Paper Submission

The WMED organizers would like to announce that the Final Paper submission due date has been extended to **Friday, March 17th**. The WMED organizing committee decided that it needed more paper submissions for an improved contributing sessions and poster sessions. For these reasons, the active participation of industry and academic authors within the Pacific Northwest region is strongly encouraged. With this final extension of the due date, the authors of the existing submissions can edit and modify their work up to the deadline.

We continue to solicit 2-page paper in the IEEE Electron Device Letters format. Remember that the published material can be a “work in a progress” status. More information is found on the WMED website in the following link:


The WMED 2006 Tutorial and Invited Speakers are listed below:

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<tr>
<th>KEYNOTE SPEAKER</th>
<th>“Future Directions of Non-Volatile Memory Technologies”</th>
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<tr>
<td>Al Fazio; Director, Memory Technology Development, Intel Corp.</td>
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<tr>
<th>TUTORIAL SPEAKERS</th>
<th>“Current Reliability and Failure Analysis Issues for High Volume Memory Products”</th>
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<tr>
<td>Christopher L. Henderson; President, Semitracks Inc.</td>
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<tr>
<td>Nozad Karim; VP of Application Engineering and Characterization, Amkor Technology Inc.</td>
<td>“3D Memory Packaging Technologies &amp; Trends”</td>
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<th>INVITED SPEAKERS</th>
<th>“Preserving Low-k Dielectrics During Photoresist and Etch Residue Removal”</th>
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<td>Dennis Hess; William W. LaRoche, Jr. Chair, School of Chemical &amp; Biomolecular Engineering, Georgia Tech</td>
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<tr>
<td>Karl Strauss; Senior Engineer, Flight Avionics Systems, Jet Propulsion Laboratory</td>
<td>“Lest We Never Forget: A Historical Perspective of Space Data Recorders; A Prediction for the Future”</td>
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<tr>
<td>Neil Goldman; Professor, Department of Electrical Engineering; Univ. Of Maryland at College Park</td>
<td>“Physics Based Modeling and Design of Chips, Devices, and Nanostructures: Present and Future”</td>
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</table>

Best Regards,

Fernando Gonzalez
Sr. Technical Member
Process R&D Thin Films Department
Micron Technology, Inc.
IEEE/EDS WMED Publicity Chair

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